

Description

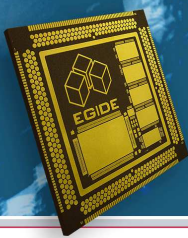
Egide's multilayer ceramic insert packages meet the high performance requirements for 2.5Gb/s & 10Gb/s Transmitter Optical Sub-Assembly (TOSA) & Receiver Optical Sub-Assembly (ROSA). These are designed for use with XFP, X2, XPAK and XENPAK transceivers, 300pin transponders for WDM (IR2/LR2), TDM or 10GbE applications and OC192/STM-64 SONET/SDH Metro or Long Reach line cards. The low form factor packages are compatible with the demanding specifications of the XMD MSA standard for DFB, FP and EML-based TOSA products as well as PIN-TIA or APD-TIA-based ROSA products. Customized designs upon request.



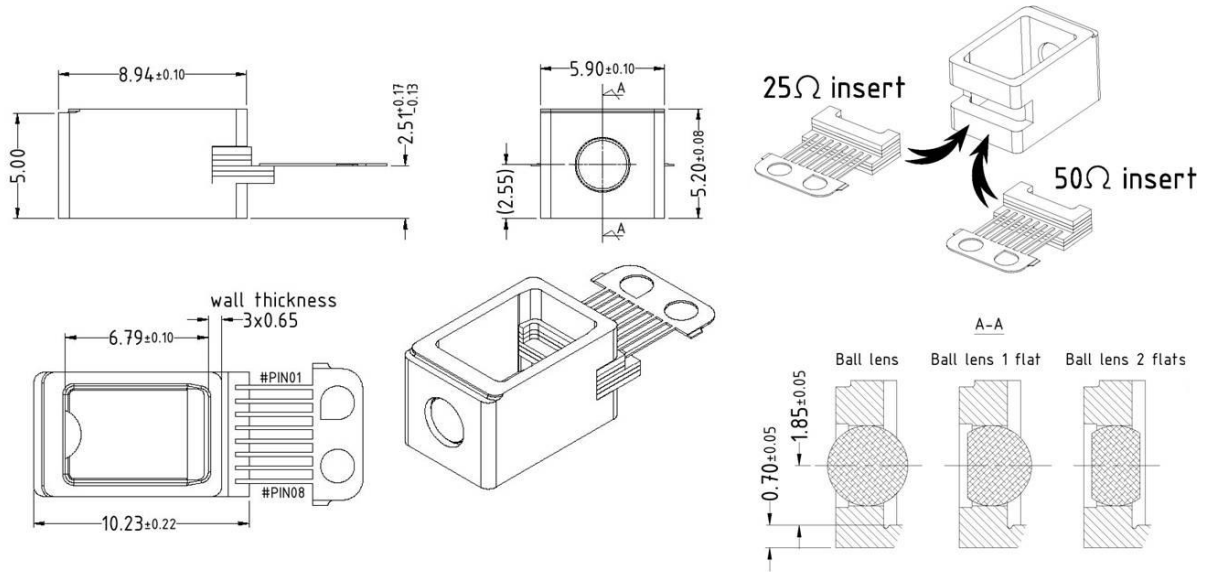
Features

- Ultra compact design compliant with XMD MSA standard package definition.
- Standard 25 Ω or 50 Ω impedance matched ceramic inserts; customized insert available upon request
- Open tool standards
- Compatible with 2.5Gb/s and 10Gb/s data rates
- Full moulded Kovar body
- CuW base available upon request
- Integrated lens assembly
- Customized designs upon request.

Contact : sales@egide.fr – sales@egideusa.com
www.egideusa.com - www.egide.fr

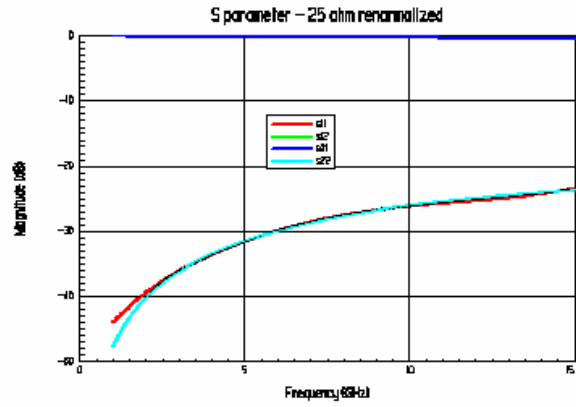
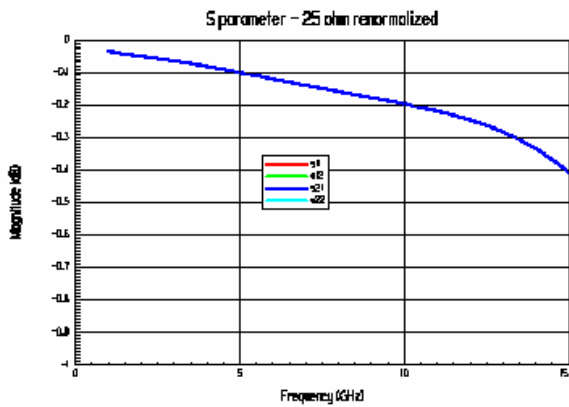
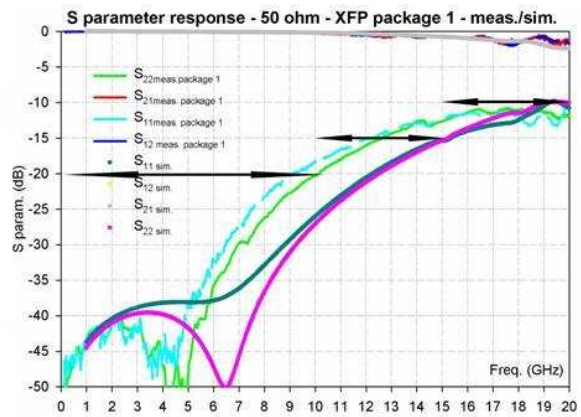
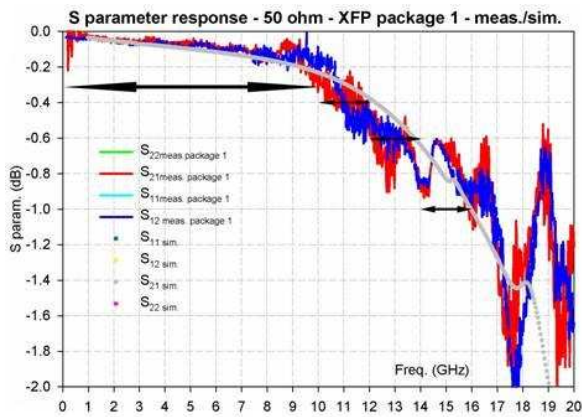


Package outline (example)



dimensions in mm

High frequency performance



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